TEXAS INSTRUMENTS

Data sheet acquired from Harris Semiconductor
SCHS270A

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CD54/74FCT240, CD54/74FCT240AT, CD54/74FCT241, CD54/74FCT244, CD54/74FCT244AT

FCT Interface Logic
Octal Buffers/Line Drivers, Three-State

Features

- **CD54/74FCT240, CD54/74FCT240AT - Inverting**
- **CD54/74FCT241, CD54/74FCT244, CD54/74FCT244AT - Non-Inverting**
- **Buffered Inputs**
- **Typical Propagation Delay: 4.1ns at VCC = 5V, TA = 25°C (FCT240AT, FCT244AT)**
- **SCR-Latchup-Resistant BiCMOS Process and Circuit Design**
- **FCTXXX Types - Speed of Bipolar FAST®/AS/S; FCTXXXAT Types - 30% Faster Than FAST/AS/S with Significantly Reduced Power Consumption**
- **48mA to 64mA Output Sink Current (Commercial/Extended Industrial)**
- **Output Voltage Swing Limited to 3.7V at VCC = 5V**
- **Controlled Output-Edge Rates**
- **Input/Output Isolation to VCC**
- **BiCMOS Technology with Low Quiescent Power**

Ordering Information

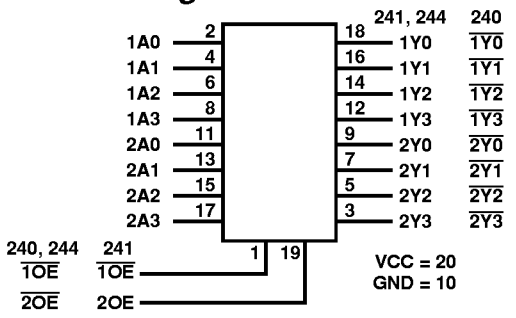
PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54/74FCT240E	-55 to 125, 0 to 70	20 Ld PDIP
CD54/74FCT240ATE	-55 to 125, 0 to 70	20 Ld PDIP
CD54/74FCT241E	-55 to 125, 0 to 70	20 Ld PDIP
CD54/74FCT244E	-55 to 125, 0 to 70	20 Ld PDIP
CD54/74FCT244ATE	-55 to 125, 0 to 70	20 Ld PDIP
CD54/74FCT240M	-55 to 125, 0 to 70	20 Ld SOIC
CD54/74FCT240ATM	-55 to 125, 0 to 70	20 Ld SOIC
CD54/74FCT241M	-55 to 125, 0 to 70	20 Ld SOIC
CD54/74FCT244M	-55 to 125, 0 to 70	20 Ld SOIC
CD54/74FCT244ATM	-55 to 125, 0 to 70	20 Ld SOIC
CD54/74FCT240SM	-55 to 125, 0 to 70	20 Ld SSOP
CD54/74FCT241SM	-55 to 125, 0 to 70	20 Ld SSOP
CD54/74FCT244SM	-55 to 125, 0 to 70	20 Ld SSOP
CD54FCT240H	-55 to 125	
CD54FCT241H	-55 to 125	
CD54FCT244H	-55 to 125	

Description

The CD54/74FCT240, 240AT, 241, 244 and 244AT three-state octal buffers/line drivers use a small-geometry BiCMOS technology. The output stage is a combination of bipolar and CMOS transistors that limits the output-HIGH level to two diode drops below VCC. This resultant lowering of output swing (0V to 3.7V) reduces power bus ringing (a source of EMI) and minimizes VCC bounce and ground bounce and their effects during simultaneous output switching. The output configuration also enhances switching speed and is capable of sinking 48mA to 64mA.

The CD54/74FCT240, 240AT, 244 and 244AT have active-LOW output enables ($\overline{1OE}$, $\overline{2OE}$). The CD54/74FCT241 and CD54/74FCT241AT have one active-LOW ($\overline{1OE}$) and one active-HIGH (2OE) output enable.

Functional Diagram



CD54/74FCT240, CD54/74FCT240AT TRUTH TABLE

INPUT	INPUT	OUTPUT
$\overline{1OE}$, $\overline{2OE}$	A	$\overline{Y}$
L	L	H
L	H	L
H	X	Z

CD54/74FCT244, CD54/74FCT244AT TRUTH TABLE

INPUT	INPUT	OUTPUT
$\overline{1OE}$, $\overline{2OE}$	A	Y
L	L	H
L	H	L
H	X	Z

CD54/74FCT241 TRUTH TABLE

INPUT		OUTPUT	INPUT		OUTPUT
$\overline{1OE}$	1A	1Y	2OE	2A	2Y
L	L	L	L	X	Z
L	H	H	H	L	L
H	X	Z	H	H	H

NOTE: H = High Voltage Level, L = LOW Voltage Level
X = Immaterial, Z = HIGH Impedance

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CAUTION: These devices are sensitive to electrostatic discharge. Users should follow proper IC Handling Procedures.

File Number **2227.3**

Switching Specifications FCT Series tr, tf = 2.5ns, C_L = 50pF, R_L - See Figure 2

PARAMETER		SYMBOL	V_{CC} (V)	+25°C	0°C to +70°C		-55°C to +125°C		+25°C	0°C to +70°C		-55°C to +125°C		UNITS
				TYP	MIN	MAX	MIN	MAX	TYP	MIN	MAX	MIN	MAX	
Propagation Delays														
Data to Outputs	FCT240/AT	t_{PLH}, t_{PHL}	5†	5	1.5	8	1.5	9	4.4	1.5	5.6	1.5	6.7	ns
	FCT241	t_{PLH}, t_{PHL}	5	4	1.5	6.5	1.5	7	-	-	-	-	-	ns
	FCT244/AT	t_{PLH}, t_{PHL}	5	4.5	1.5	6.5	1.5	7	3.8	1.5	5.3	1.5	6.2	µs
Output Enable Times	FCT240/AT	t_{PZL}, t_{PZH}	5	7	1.5	10	1.5	10.5	4.7	1.5	6.2	1.5	7.7	µs
	FCT241	t_{PZL}, t_{PZH}	5	5.5	1.5	8	1.5	8.5	-	-	-	-	-	ns
	FCT244/AT	t_{PZL}, t_{PZH}	5	6	1.5	8	1.5	8.5	4.8	1.5	6.5	1.5	7.8	ns
Output Disable Times	FCT240/AT	t_{PLZ}, t_{PHZ}	5	6	1.5	9.5	1.5	10	4	1.5	5.6	1.5	6.5	µs
	FCT241	t_{PLZ}, t_{PHZ}	5	4.5	1.5	7	1.5	7.5	-	-	-	-	-	ns
	FCT244/AT	t_{PLZ}, t_{PHZ}	5	5	1.5	7	1.5	7.5	4.5	1.5	5.8	1.5	6.8	µs
Power Dissipation Capacitance	FCT240/AT	C_{PD}§	-	38 Typical					38 Typical					pF
	FCT241	C_{PD}§	-	33 Typical					-					pF
	FCT244/AT	C_{PD}§		35 Typical					35 Typical					pF
Min. (Valley) V_{OHV} During Switching of Other Outputs (Output Under Test Not Switching)		V_{OHV} See Figure 1	5	0.5 Typical at +25°C										V
Max. (Peak) V_{OLP} During Switching of Other Outputs (Output Under Test Not Switching)		V_{OLP} See Figure 1	5	1 Typical at +25°C										V
Input Capacitance		C_I	-	-	-	10	-	10	-	-	10	-	10	pF
3-State Output Capacitance		C_O	-	-	-	15	-	15	-	-	15	-	15	pF

† 5V: min. is at 5.5V, max. is at 4.5V.
5V: min. is at 5.25V for 0°C to +70°C, max. is at 4.75V for 0°C to +70°C, typ. is at 5V

§ C_{PD}, measured per function, is used to determine the dynamic power consumption. P_D (per package) = V_{CC} I_{CC} + Σ (V_{CC}^2 fi C_{PD} + V_O^2 fo C_L + V_{CC} ΔI_{CC} D) where:

V_{CC} = supply voltage
ΔI_{CC} = flow through current x unit load
C_L = output load capacitance
D = duty cycle of input high
fo = output frequency
fi = input frequency

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